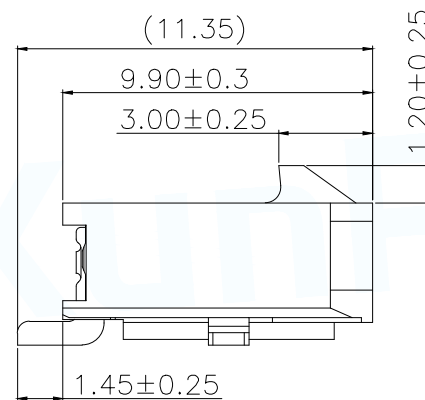
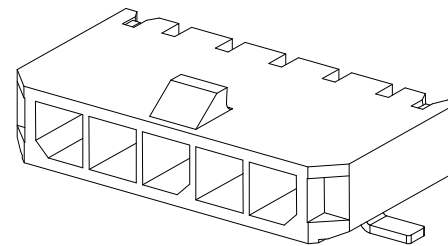
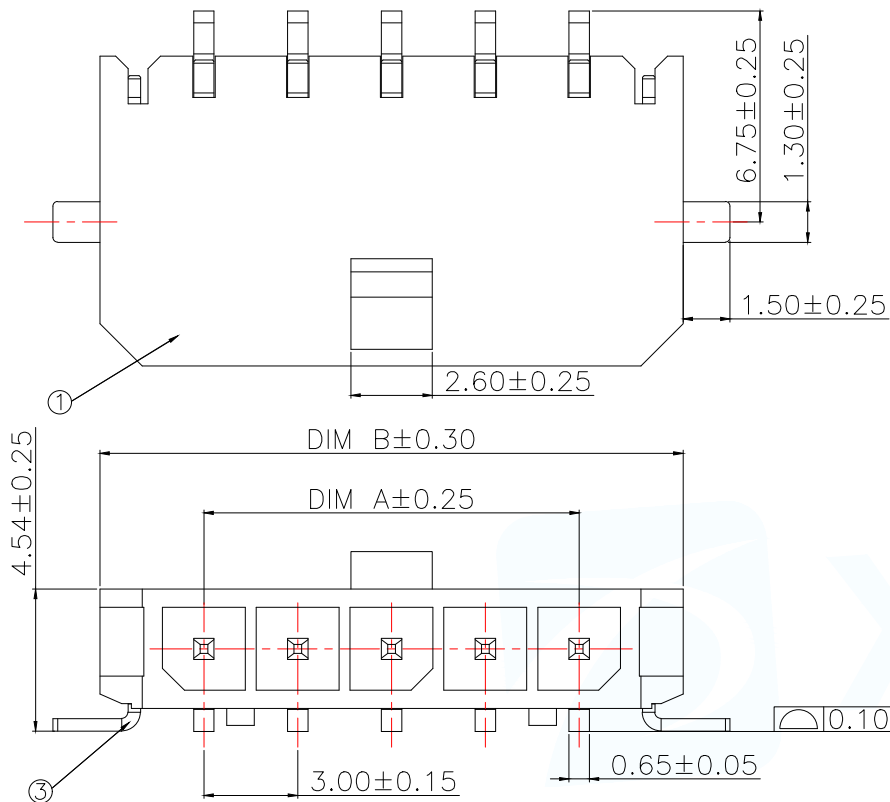
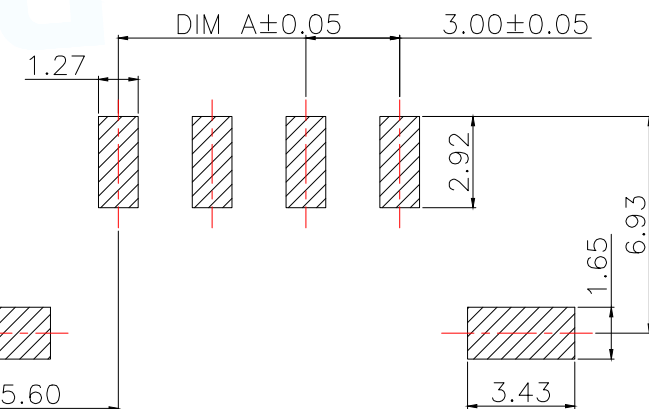




型号	CKT	A	B
WAfer-NX3.0-2PWB	2	3.00	9.65
WAfer-NX3.0-3PWB	3	6.00	12.65
WAfer-NX3.0-4PWB	4	9.00	15.65
WAfer-NX3.0-5PWB	5	12.00	18.65
WAfer-NX3.0-6PWB	6	15.00	21.65
WAfer-NX3.0-7PWB	7	18.00	24.65
WAfer-NX3.0-8PWB	8	21.00	27.65
WAfer-NX3.0-9PWB	9	24.00	30.65
WAfer-NX3.0-10PWB	10	27.00	33.65
WAfer-NX3.0-11PWB	11	30.00	36.65
WAfer-NX3.0-12PWB	12	33.00	39.65



P.C.B Layout

技术指标:

1. 温度范围: $-25^{\circ}\text{C} \sim 85^{\circ}\text{C}$.
2. 额定电流: 5.0A AC DC.
3. 额定电压: 250V AC DC.
4. 耐电压: 1000V AC/minute.
5. 接触电阻: $\leq 20\text{m}\Omega$.
6. 绝缘电阻: $\geq 1000\text{M}\Omega$.

MANUFACTURE DWG

东莞市讯普电子科技有限公司
DongGuan XunPu Electronics Co., Ltd

序号	品名	材质
①	MX3.0单排卧式脱芯	LCP UL94V-0 黑色
②	MX3.0单排卧式端子	铜合金/表面镀锡
③	MX3.0单排卧式焊片	铜合金/表面镀锡

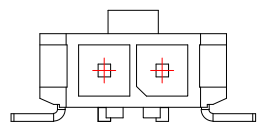
UNLESS OTHERWISE SPECIFIED TOLERANCES	
DECIMALS:	ANGLES:
X.: ± 0.50	$\pm 1^{\circ}$
X.X: ± 0.20	
X.XX: ± 0.10	



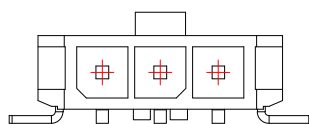
TITLE:		
MX3.0单排卧式		
PAR	WAfer-NX3.0-NPWB	
DWN	Lucas	
CHKD	Ethan	
APVD	Jacob	
SCALE:1:1	UNIT:MM	
SIZE:A4	SHEET:1F1	REV:A

ROHS Compliant

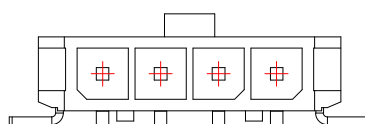
MAPX	MODIFICATION	DATE	DRAW	APPROVE



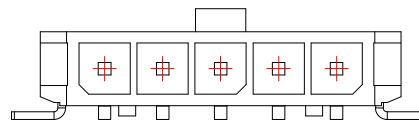
2PIN



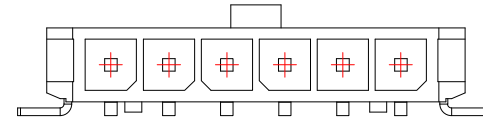
3PIN



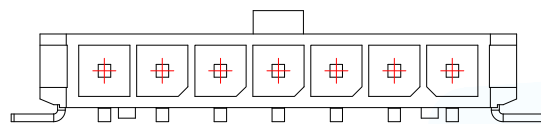
4PIN



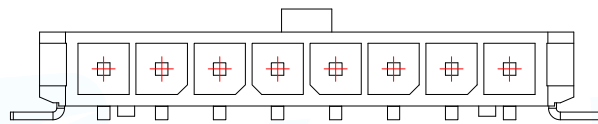
5PIN



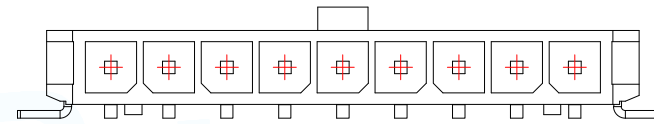
6PIN



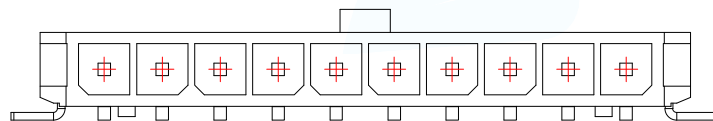
7PIN



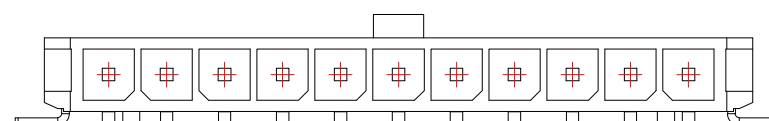
8PIN



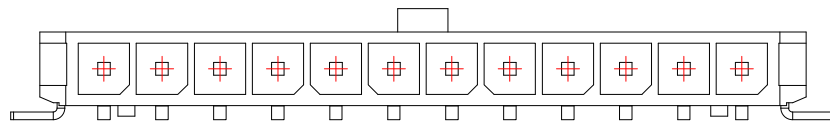
9PIN



10PIN



11PIN



12PIN

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: MX3.0单排卧式		
			PAR	WAFER-NX3.0-NPWB	
DECIMALS:			DWN	Lucas	
X.:±0.50			CHKD	Ethan	
X.X:±0.20			APVD	Jacob	
X.XX:±0.10		CUSTOMER COPY	SCALE:1:1	UNIT:MM	
			SIZE:A4	SHEET:1F1	REV:A